



2SK2661

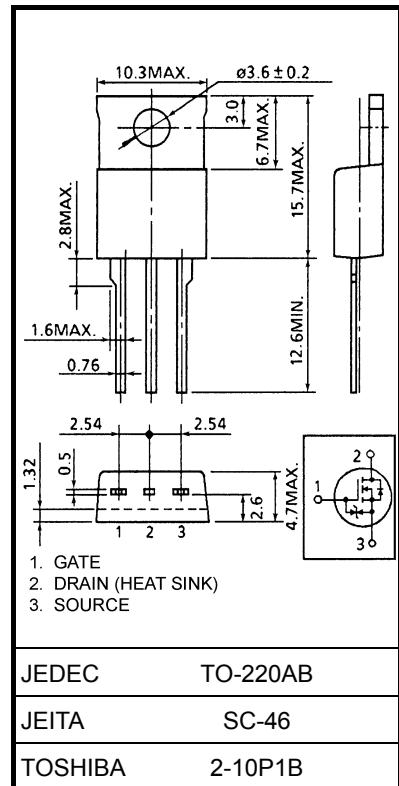
Chopper Regulator, DC–DC Converter and Motor Drive Applications

Unit: mm

- Low drain–source ON resistance : $R_{DS\ (ON)} = 1.35 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 4.0 \text{ S}$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu\text{A}$ (max) ($V_{DS} = 500 \text{ V}$)
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Drain–source voltage	V_{DSS}	500	V
Drain–gate voltage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	500	V
Gate–source voltage	V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	A
	Pulse (Note 1)	I_{DP}	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)	P_D	75	W
Single pulse avalanche energy (Note 2)	E_{AS}	180	mJ
Avalanche current	I_{AR}	5	A
Repetitive avalanche energy (Note 3)	E_{AR}	7.5	mJ
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55~150	$^\circ\text{C}$



Weight: 2.0 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	1.67	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	83.3	$^\circ\text{C} / \text{W}$

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 12.2 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 5 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

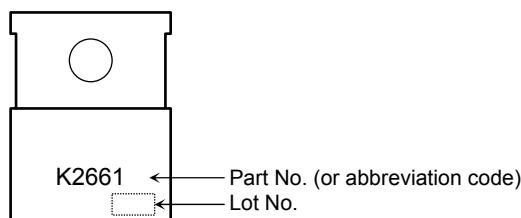
Please handle with caution.

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	—	—	±10	µA	
Gate–source breakdown voltage	V (BR) GSS	I _G = ±10 µA, V _{DS} = 0 V	±30	—	—	V	
Drain cut-off current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	—	—	100	µA	
Drain–source breakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	—	—	V	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V	
Drain–source ON resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.5 A	—	1.35	1.50	Ω	
Forward transfer admittance	Y _{fsl}	V _{DS} = 10 V, I _D = 2.5 A	2.5	4.0	—	S	
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	—	780	—	pF	
Reverse transfer capacitance	C _{rss}		—	60	—		
Output capacitance	C _{oss}		—	200	—		
Switching time	Rise time	t _r	 V _{GS} 10V 0V R _L = 90Ω V _{DD} = 225V Duty ≤ 1%, t _w = 10µs	—	12	—	ns
	Turn-on time	t _{on}		—	25	—	
	Fall time	t _f		—	15	—	
	Turn-off time	t _{off}		—	60	—	
Total gate charge (gate–source plus gate–drain)	Q _g	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 5 A	—	17	—	nC	
Gate–source charge	Q _{gs}		—	11	—		
Gate–drain (“miller”) Charge	Q _{gd}		—	6	—		

Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	—	—	5	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	—	—	20	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	—	—	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / µs	—	1400	—	ns
Reverse recovery charge	Q _{rr}		—	9	—	µC

Marking

A line indicates
lead (Pb)-free package or
lead (Pb)-free finish.

